



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Forester, et al.

Attorney Docket: TI-32569

COPY OF PAPERS
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Examiner: TBD

Serial No.: 10/026,052

Art Unit: TBD

Title: Low Cost Area Array Probe for Circuits Having Solder-Ball Contacts
Manufactured Using a Wire Bonding Machine

Certificate of Mailing

I hereby certify that this correspondence is being deposited with the United States Postal Service as First Class Mail in an envelope addressed to: Commissioner of Patents, Washington, D.C. 20231.

Karen Fabritiis
Karen Fabritiis

3/1/2002
Date

Commissioner for Patents
Washington, DC 20231

PRELIMINARY AMENDMENT

Dear Sir:

Prior to examination on the merits, Applicant respectfully submits this Preliminary Amendment and remarks as set forth below:

In the Specification:

Please replace the paragraph beginning at line 10 of page 7 with the following rewritten paragraph:

Figure 18a illustrates an alternate embodiment for providing pathways from the conductive pads with the stud bumps to testing circuitry.

Please replace the paragraph beginning at line 15 of page 13 with the following rewritten paragraph:

It should be appreciated, however, that the conductive pathways 64g could be formed on the back-side of the substrate such as on the surface 66 opposite the working surface 42 as shown in Figure 18a. To accomplish this, there will also be a conductive path 68 from the conductive pad 40g on the working surface 42 through the substrate 44 such as by a via to the opposite surface or back side 66 of the substrate. It will also be appreciated that individual wires could be connected at the via instead of depositing conductive traces.

REMARKS

The "Notice to File Corrected Application Papers" dated January 29, 2002 considered Figure 19 to be missing. However, there was no Figure 19. The Brief Description of the Drawings on Page 3 should have included a Figure 18a, which was included, rather than a Figure 19. This correction has been made by this Preliminary Amendment. In addition, Figure 18a has been identified at the first paragraph of page 13. No new matter has been added.

Attached hereto is a copy of the January 29, 2002 Notice and a marked-up version of the changes made to the specification for the current amendment. The attached page is captioned "Version with Markings to Show Changes Made."

Respectfully submitted,



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VERSION WITH MARKINGS TO SHOW CHANGES MADE

In the Specification:

Please replace the paragraph beginning at line 10 of page 7 with the following rewritten paragraph:

Figure [19] 18a illustrates an alternate embodiment for providing pathways from the conductive pads with the stud bumps to testing circuitry.

Please replace the paragraph beginning at line 15 of page 13 with the following rewritten paragraph:

It should be appreciated, however, that the conductive pathways 64g could be formed on the back-side of the substrate such as on the surface 66 opposite the working surface 42 as shown in Figure 18a. To accomplish this, there will also be a conductive path 68 from the conductive pad 40g on the working surface 42 through the substrate 44 such as by a via to the opposite surface or back side 66 of the substrate. It will also be appreciated that individual wires could be connected at the via instead of depositing conductive traces.